



ENFIS UNO Plus Array Infra-Red (NIR) 870nm

Smart, powerful, compact, efficient, reliable light

Features & Benefits

- Intense, high-power Infra-Red spot source
- Ultra-high power density
- Long-life and reliable, high-performance due to excellent thermal conductivity
- Simple integration via connectorized PCB with mounting holes

Outline Specification

- 5000mW Typical power
- 1.15cm² Aperture
- 4348mW/cm² Power density
- Input Power: 50W
- Typical thermal resistance <0.8°C/W

Light Engine Integration

Enfis can eliminate the time, cost and risk of integration by offering our arrays as part of a complete light engine solution

Smart Array Technology

Light output from the Enfis arrays can be monitored and controlled via patent-pending integrated photo-detection system, enabling precise control of light output.

Thermal Management

Enfis arrays are designed to provide excellent thermal conductivity and to be integrated effectively with thermal hardware to ensure optimum performance and life

Optics

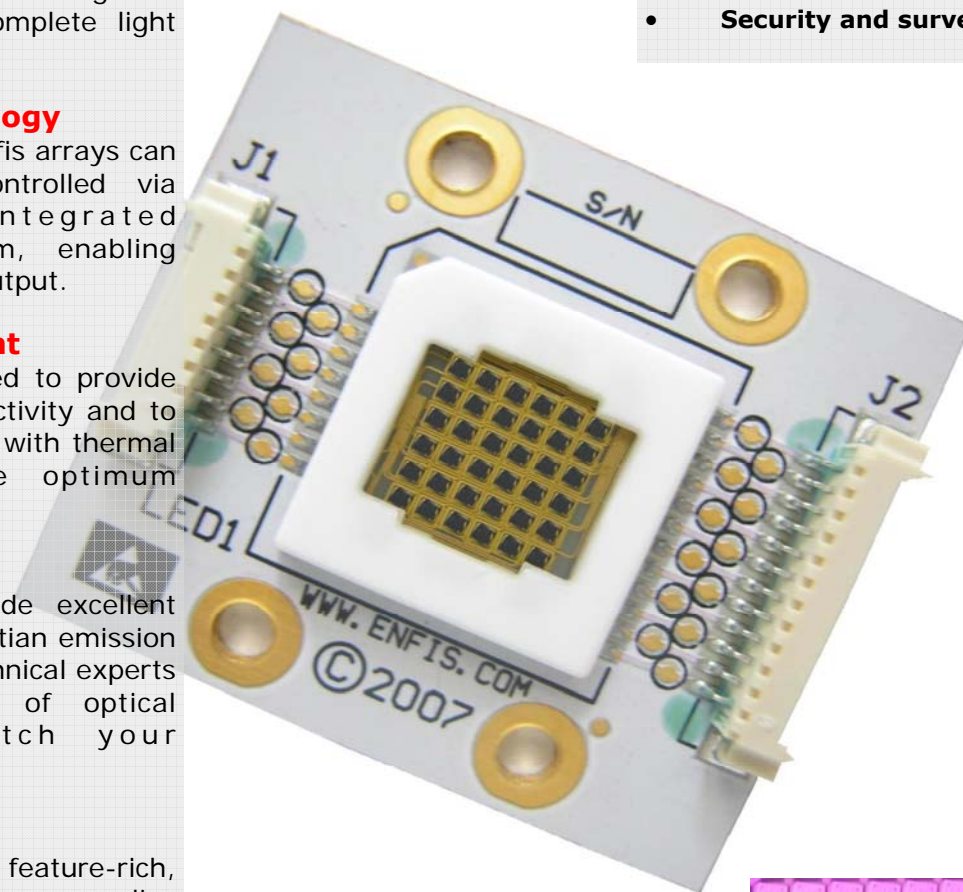
Enfis Uno arrays provide excellent spot source with Lambertian emission characteristics. Enfis technical experts can advise a range of optical solutions to match your requirements.

Power Management

Enfis provides a range of feature-rich, powerful drivers and power supplies for our arrays. Our applications team can provide you with a solution for your specific requirements.

Applications & Markets

- Medical applications
- Security and surveillance



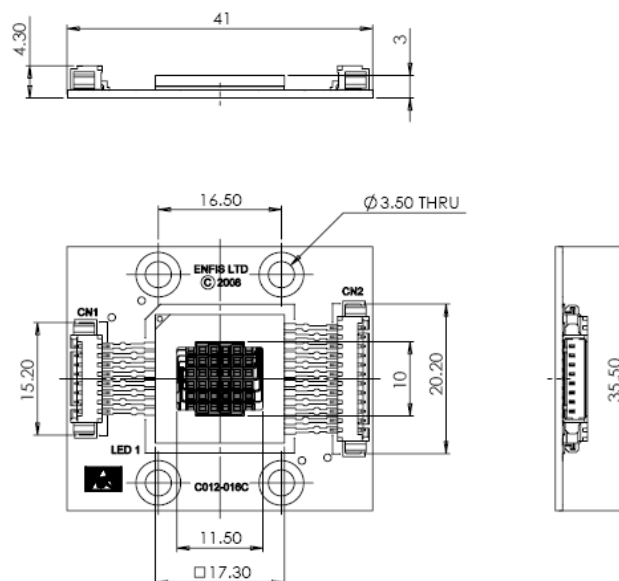


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Technical Specification

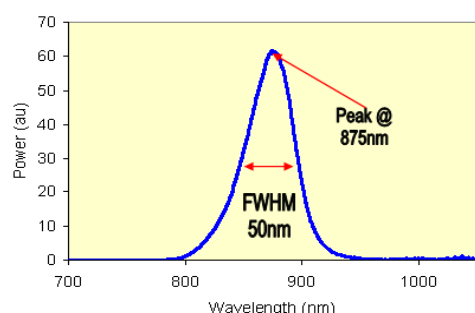
Electro-Optical Characteristics

Item	Min	Typ	Max
Rated Current If (mA)		2950	
Forward Voltage Vf (Volts)	14	17	21
Peak Wavelength λ_p (nm)	850	870	890
Spectral Width $\Delta\lambda$ (nm)	40	50	60
Total Radiant Flux Φ_R (mW)	4500	5000	
Radiant Flux Density Φ_R/A (mW/cm ²)	3913	4348	
Total Electrical Power P (W)		50	

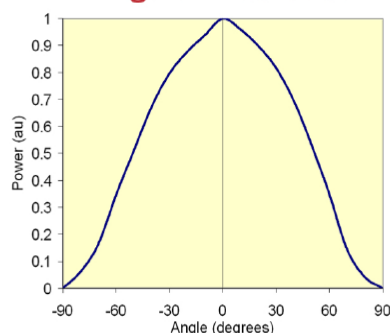


All measurements performed at a heatsink temperature of 25°C

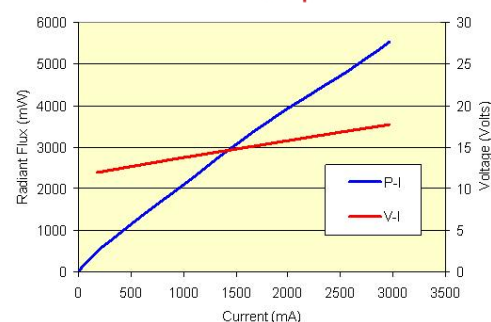
Spectral Data



Angular Distribution



LIV Graph



Heat Generation

Proper thermal design of the end product is of paramount importance. The operational junction temperature of each LED chip should be kept below 125°C.

Please contact Enfis for further support in this matter.

Handling LED Array

Contact with the encapsulation on the surface of the LED array must be avoided to prevent damage. Do not apply pressure to the encapsulation or allow it to come into contact with sharp objects. During operation the encapsulation will be hot and contact should be avoided.

Static Electricity

Care must be taken when handling, these products are sensitive to static electricity.

Observe static handling precautions.



Cleaning

Avoid touching the LED array surface.

To clean—BLOW surface with either dry air or nitrogen gas

Eye Safety Precautions

The light output of the products may cause injuries to human eyes in circumstances where the products are viewed directly with unshielded eyes for more than a few seconds.

Please refer to IEC 60825-1:2001 for further information

